

#### **General Description**

The MAX3430 fault-protected RS-485 transceiver features ±80V protection from overvoltage signal faults on communication bus lines. Each device contains one driver and one receiver, and the output pins can withstand faults, with respect to ground, of up to ±80V. Even if the faults occur when the transceiver is active, shut down, or powered off, the device will not be damaged. The MAX3430 operates from a 3.3V supply and features a slew-rate-limited driver that minimizes EMI and reduces reflections caused by improperly terminated cables, allowing errorfree data transmission at data rates up to 250kbps. The MAX3430 has a 1/4-unit-load receiver input impedance allowing up to 128 transceivers on a single bus and features fail-safe circuitry, which guarantees a logic-high receiver output when the receiver inputs are open.

Hot-swap circuitry eliminates false transitions on the data cable during circuit initialization or connection to a live backplane. Short-circuit current limiting and thermal-shutdown circuitry protect the driver against excessive power dissipation.

The MAX3430 is available in 8-pin SO and 8-pin PDIP packages, and is specified over commercial and industrial temperature ranges.

#### **Applications**

RS-422/RS-485 Communications Lighting Systems Industrial-Control Local Area Networks **Profibus Applications** Multimaster RS-485 Networks

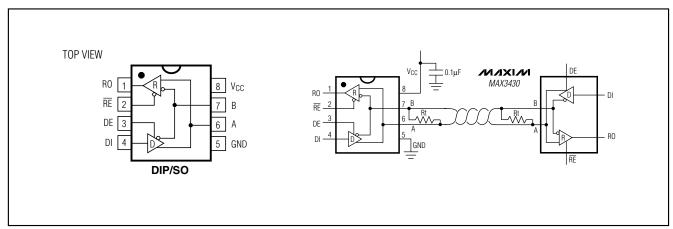
#### **Features**

- ♦ ±80V Fault Protection
- ♦ ±12kV ESD Protection
- ♦ +3.3V Operation
- ♦ Internal Slew-Rate Limiting
- ♦ 250kbps Data Rate
- ♦ Allows Up to 128 Transceivers on the Bus
- ◆ -7V to +12V Common-Mode Input Voltage Range
- ♦ True Fail-Safe Inputs
- ♦ Hot-Swap Input Structure on DE
- ♦ Available in 8-Pin SO and PDIP Packages

#### **Ordering Information**

PART	TEMP RANGE	PIN-PACKAGE
MAX3430CPA	0°C to +70°C	8 Plastic DIP
MAX3430CSA	0°C to +70°C	8 SO
MAX3430EPA	-40°C to +85°C	8 Plastic DIP
MAX3430ESA	-40°C to +85°C	8 SO

### Pin Configuration and Typical Operating Circuit



MIXIM

#### **ABSOLUTE MAXIMUM RATINGS**

(All voltages are referenced to GND.)
V <sub>C</sub> C+5
RE, DE, DI0.3V to (V <sub>CC</sub> + 0.3V
Driver Output Voltage (A, B) (Note 1)±80
Receiver Input Voltage (A, B) (Note 1)±80'
RO0.3V to (V <sub>CC</sub> + 0.3V
Continuous Power Dissipation ( $T_A = +70^{\circ}C$ )
8-Pin SO (derate 5.88mW/°C above +70°C)471mV
8-Pin Plastic DIP (derate 9.09mW/°C above +70°C)727mV

Operating Temperature Range	es
MAX3430C	0°C to +70°C
MAX3430E	40°C to +85°C
Junction Temperature	+150°C
	65°C to +150°C
Lead Temperature (soldering,	10s)+300°C

**Note 1:** A, B must be terminated with  $54\Omega$  or  $100\Omega$  to guarantee  $\pm 80V$  fault protection.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### DC ELECTRICAL CHARACTERISTICS

 $(V_{CC} = +3.3V \pm 10\%, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted.}$  Typical values are at  $V_{CC} = +3.3V \text{ and } T_A = +25^{\circ}C.)$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
DRIVER	1		•				
Differential Driver Output	Van	Figure 1, $R_L = 100\Omega$	2.0		Vcc	V	
Differential Driver Output Voc		Figure 1, $R_L = 54\Omega$			Vcc		
Change in Magnitude of Differential Output Voltage	ΔV <sub>OD</sub>	V <sub>OD</sub> Figure 1, R <sub>L</sub> = 100 $\Omega$ or 54 $\Omega$ (Note 2)			0.2	V	
Driver Common-Mode Output Voltage	Voc	Figure 1, $R_L = 100\Omega$ or $54\Omega$		V <sub>CC</sub> / 2	3	V	
Change in Magnitude of Common-Mode Voltage	ΔV <sub>OC</sub>	Figure 1, $R_L = 100\Omega$ or $54\Omega$ (Note 2)			0.2	V	
DRIVER LOGIC			•				
Driver Input High Voltage	VIH	DI	2.0			V	
Driver Input Low Voltage	V <sub>I</sub> L	DI			0.8	V	
Driver Input Current	I <sub>IN</sub>	DI			±1	μΑ	
Driver Short-Circuit Output	losp	0 ≤ V <sub>OUT</sub> ≤ 12V (Note 3)	-		+250	mA	
Current	1080	-7V ≤ V <sub>OUT</sub> ≤ V <sub>CC</sub> (Note 3) -250				IIIA	
Driver Short-Circuit Foldback	losdf	$(V_{CC} - 1V) \le V_{OUT} \le 12V \text{ (Note 3)}$	+10			mΛ	
Output Current	IOSDF	-7V ≤ V <sub>OUT</sub> ≤ 1V (Note 3)	(Note 3)		-10	mA	
RECEIVER							
		$DE = GND$ , $\overline{RE} = GND$ , $V_{IN} = +12V$			250		
Input Current (A, B)	I <sub>A, B</sub>	$DE = GND$ , $\overline{RE} = GND$ , $V_{IN} = -7V$			-200	μA 00	
		$V_{IN} = -80V \text{ to } +80V$	-6		+6	mA	
Receiver Differential Threshold Voltage	V <sub>TH</sub>	-7V ≤ V <sub>CM</sub> ≤ 12V -20			-50	mV	
Receiver Input Hysteresis	$\Delta V_{TH}$	$V_A + V_B = 0$		25	•	mV	

#### **DC ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{CC} = +3.3V \pm 10\%, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } V_{CC} = +3.3V \text{ and } T_A = +25^{\circ}C.)$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
RECEIVER LOGIC			·			
RO Output High Voltage	Voн	I <sub>O</sub> = -1.6mA	V <sub>CC</sub> - 0.6			V
RO Output Low Voltage	V <sub>OL</sub>	I <sub>O</sub> = 1mA			0.4	V
Three-State Output Current at Receiver	lozr	ZR 0 ≤ V <sub>O</sub> ≤ V <sub>CC</sub>			± 1	μΑ
Receiver Input Resistance	R <sub>IN</sub>	-7V ≤ V <sub>CM</sub> ≤ 12V	48			kΩ
Receiver Output Short-Circuit Current	Iosr	0 ≤ V <sub>RO</sub> ≤ V <sub>CC</sub>			±95	mA
CONTROL			<u>.</u>			
Control Input High Voltage	VCIH	DE, RE	2.0			V
Control Input Low Voltage	VCIL	DE, RE			0.8	V
Input Current DE Current Latch During First DE Rising Edge				80		μΑ
Input Current RE Current Latch During First RE Rising Edge				80		μΑ

#### **PROTECTION SPECIFICATIONS**

 $(V_{CC} = +3.3V \pm 10\%, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } V_{CC} = +3.3V \text{ and } T_A = +25^{\circ}C.)$ 

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
ESD Protection		A, B Human Body Model			±12		kV
SUPPLY CURRENT	SUPPLY CURRENT						
		No loa	ad, $\overline{RE} = 0$ , DE = V <sub>CC</sub> , DI = 0 or V <sub>CC</sub>		3.5	10	
Supply Current	Icc	No load, $\overline{RE} = V_{CC}$ , $DE = V_{CC}$ , $DI = 0$ or $V_{CC}$			3.0	8	mA
Supply Current in Shutdown Mode	Ishdn	$\overline{RE} = V_{CC}$ , $DE = 0$				200	μΑ

#### **DRIVER SWITCHING CHARACTERISTICS**

 $(V_{CC} = +3.3V \pm 10\%, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } V_{CC} = +3.3V \text{ and } T_A = +25^{\circ}C.)$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Driver Brons paties Delevi	tDPLH	Figures 2 and 2 D. F40 C. F0nF		700	1500	
Driver Propagation Delay	tdphl	Figures 2 and 3, $R_L = 54\Omega$ , $C_L = 50pF$		700	1500	ns
Driver Differential Output Rise or Fall Time	t <sub>DR</sub> , t <sub>DF</sub>	$t_{DF}$ Figures 2 and 3, $R_L = 54\Omega$ , $C_L = 50pF$			1200	ns
Differential Driver Output Skew, ltdplh - tdphll	tdskew	Figures 2 and 3, $R_L = 54\Omega$ , $C_L = 50pF$		150	200	ns
Maximum Data Rate			250			kbps
Driver Enable to Output Low	t <sub>DZL</sub>	Figure 4, C <sub>L</sub> = 50pF			5200	ns
Driver Disable Time from Output Low	tDLZ	Figure 4, C <sub>L</sub> = 50pF			1000	ns
Driver Output Enable Time from Shutdown	t <sub>DZL</sub> (SHDN)	Figure 4, C <sub>L</sub> = 50pF			8000	ns
Driver Enable to Output High	tDZH	Figure 5, C <sub>L</sub> = 50pF			5200	ns
Driver Disable Time from Output High	t <sub>DHZ</sub>	Figure 5, C <sub>L</sub> = 50pF			1000	ns
Driver Output Enable Time from Shutdown	<sup>†</sup> DZH(SHDN)	Figure 5, C <sub>L</sub> = 50pF			8000	ns
Driver Time to Shutdown	tshdn				1000	ns

#### RECEIVER SWITCHING CHARACTERISTICS

 $(V_{CC} = +3.3V \pm 10\%, T_A = T_{MIN} \text{ to } T_{MAX}, \text{ unless otherwise noted. Typical values are at } V_{CC} = +3.3V \text{ and } T_A = +25^{\circ}C.)$ 

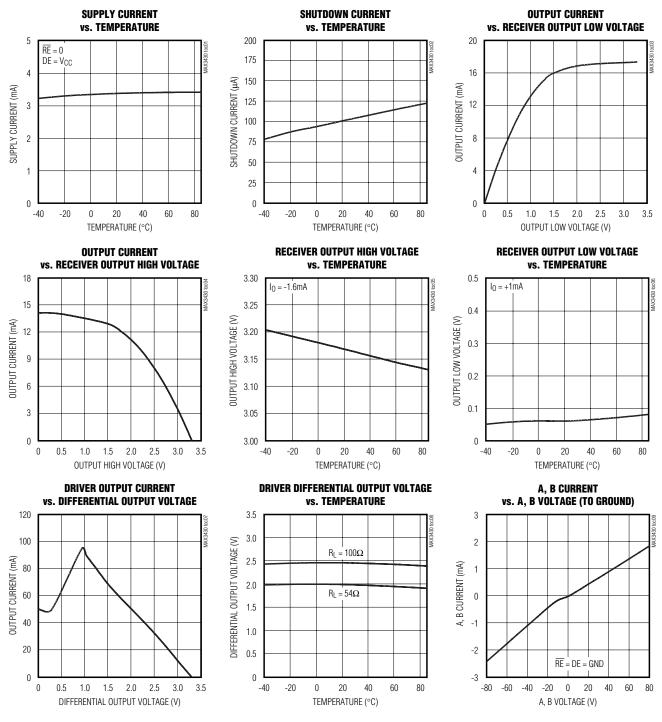
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Receiver Propagation Delay	trplh	PLH Figure C. O. 200 F. V. 20V V. 2			120	no
Receiver Propagation Delay	trphl	Figure 6, C <sub>L</sub> = 20pF, V <sub>ID</sub> = 2V, V <sub>CM</sub> = 0			120	ns
Receiver Output Skew, ltRPLH - tRPHLI	tskew	Figure 6, C <sub>L</sub> = 20pF			40	ns
Receiver Enable to Output Low	trzl	Figure 7, R = $1k\Omega$ , $C_L = 20pF$			80	ns
Receiver Enable to Output High	trzh	Figure 7, R = $1k\Omega$ , $C_L = 20pF$			80	ns
Receiver Disable Time from Low	t <sub>RLZ</sub>	Figure 7, R = $1k\Omega$ , $C_L = 20pF$			80	ns
Receiver Disable Time form High	t <sub>RHZ</sub>	Figure 7, R = $1k\Omega$ , $C_L = 20pF$			80	ns
Receiver Output Enable Time from Shutdown	trzh(shnd), trzh(shnd)	Figure 7, R = 1k $\Omega$ , C <sub>L</sub> = 20pF			5000	ns
Receiver Time to Shutdown	tshdn				1000	ns

Note 2: ΔV<sub>OD</sub> and ΔV<sub>OC</sub> are the changes in V<sub>OD</sub> and V<sub>OC</sub>, respectively, when the DI input changes state.

**Note 3:** The short-circuit output current applies to peak current just prior to foldback current limiting; the short-circuit foldback output current applies during current limiting to allow a recovery from bus contention.

#### **Typical Operating Characteristics**

 $(V_{CC} = +3.3V, T_A = +25^{\circ}C, unless otherwise noted.)$ 



### Test Circuits/Timing Diagrams

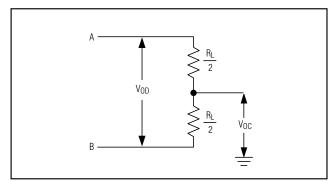


Figure 1. Driver DC Test Load

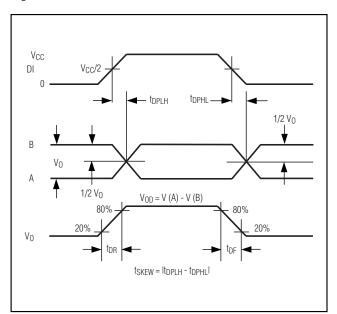


Figure 3. Driver Propagation Delays

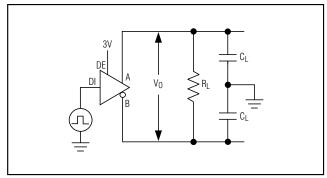


Figure 2. Driver Timing Test Circuit

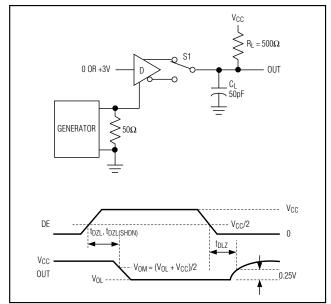


Figure 4. Driver Enable and Disable Times ( $t_{DZL}$ ,  $t_{DLZ}$ ,  $t_{DLZ}$ ,  $t_{DLZ}$ )

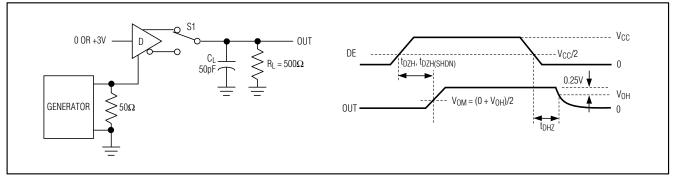


Figure 5. Driver Enable and Disable Times (tDHZ, tDZH, tDZH(SHDN))

### Test Circuits/Timing Diagrams (continued)

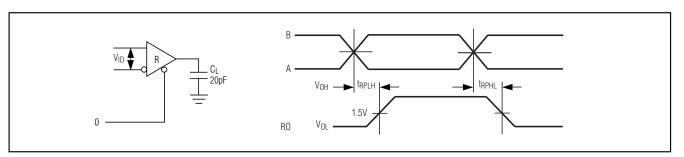


Figure 6. Receiver Propagation Delays

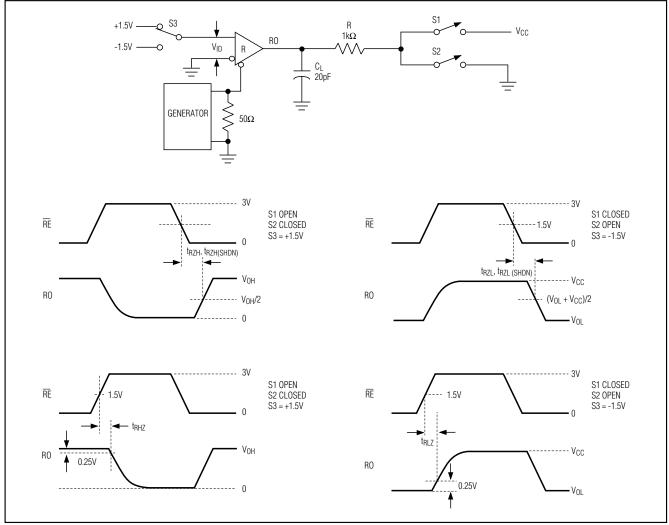


Figure 7. Receiver Enable and Disable Times

### Pin Description

PIN	NAME	FUNCTION
1	RO	Receiver Output
2	RE	Receiver Output Enable. RO is enabled when $\overline{RE}$ is low; RO is high impedance when $\overline{RE}$ is high. The device enters a low-power shutdown mode if $\overline{RE}$ is high and DE is low.
3	DE	Driver Output Enable. Driving DE high enables the driver outputs. Pulling DE low puts the driver outputs in a high-impedance state. If $\overline{\text{RE}}$ is high and DE is low, the device enters a low-power shutdown mode. If the driver outputs are enabled, the device functions as a line driver, and when they are high impedance it functions as a line receiver if $\overline{\text{RE}}$ is low.
4	DI	Driver Input. A logic low on DI forces output A low and output B high, while a logic high on DI forces output A high and output B low.
5	GND	Ground
6	А	Noninverting Receiver Input/Driver Output
7	В	Inverting Receiver Input/Driver Output
8	Vcc	Positive Supply, $V_{CC}$ = +3.3V ±10%. Bypass $V_{CC}$ to GND with a 0.1 $\mu$ F ceramic capacitor.

#### **Function Tables**

**Table 1. Transmitting** 

	INPUTS		OUTPUTS		MODE
RE	DE	DI	В	Α	MODE
Χ	1	1	0	1	Normal
Χ	1	0	1	0	Normal
0	0	Χ	High-Z	High-Z	Normal
1	0	Χ	High-Z	High-Z	Shutdown

X = Don't care.

### Table 2. Receiving

	INPUTS		OUTPUTS	MODE
RE	DE	(A - B)	RO	WODE
0	0	≥ -50mV	1	Normal
0	0	≤ -200mV	0	Normal
0	0	Inputs open	1	Normal
1	0	Χ	High-Z	Shutdown

X = Don't care.

#### Detailed Description

#### Driver

The driver accepts a single-ended, logic-level input (DI) and transfers it to a differential, RS-485 level output (A and B). Driving DE high enables the driver, while pulling DE low places the driver outputs (A and B) into a high-impedance state.

#### Receiver

The receiver accepts a differential, RS-485 level input (A and B), and transfers it to a single-ended, logic-level output ( $\overline{RO}$ ). Pulling  $\overline{RE}$  low enables the receiver, while driving  $\overline{RE}$  high and DE low places the receiver inputs (A and B) into a high-impedance state.

#### **Low-Power Shutdown**

Force DE low and  $\overline{\text{RE}}$  high to shut down the MAX3430. A time delay of 1µs prevents the device from accidentally entering shutdown due to logic skews when switching between transmit and receive modes. Holding DE low and  $\overline{\text{RE}}$  high for at least 1ms guarantees that the MAX3430 enters shutdown. In shutdown, the device consumes 100µA supply current.

#### ±80V Fault Protection

The driver outputs/receiver inputs of RS-485 devices in industrial network applications often experience voltage faults resulting from transients that exceed the -7V to +12V range specified in the EIA/TIA-485 standard. In these applications, ordinary RS-485 devices (typical absolute maximum ratings -8V to +12.5V) require costly external protection devices. To reduce system complexity and the need for external protection, the driver outputs/receiver inputs of the MAX3430 withstand voltage faults of up to ±80V with respect to ground without damage (see the *Absolute Maximum Ratings* section, Note 1). Protection is guaranteed regardless of whether the device is active, shut down, or without power.

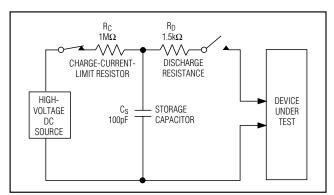


Figure 8a. Human Body ESD Test Model

#### True Fail-Safe

The MAX3430 uses a -50mV to -200mV differential input threshold to ensure true fail-safe receiver inputs. This threshold guarantees the receiver outputs a logic high for shorted, open, or idle data lines. The -50mV to -200mV threshold complies with the ±200mV threshold EIA/TIA-485 standard.

#### ±12kV ESD Protection

As with all Maxim devices, ESD-protection structures are incorporated on all pins to protect against ESD encountered during handling and assembly. The MAX3430 receiver inputs/driver outputs (A, B) have extra protection against static electricity found in normal operation. Maxim's engineers have developed state-of-the-art structures to protect these pins against ±12kV ESD without damage. After an ESD event, the MAX3430 continues working without latchup.

ESD protection can be tested in several ways. The receiver inputs are characterized for protection up to ±12kV using the Human Body Model.

#### **ESD Test Conditions**

ESD performance depends on a number of conditions. Contact Maxim for a reliability report that documents test setup, methodology, and results.

#### **Human Body Model**

Figure 8a shows the Human Body Model, and Figure 8b shows the current waveform it generates when discharged into a low impedance. This model consists of a 100pF capacitor charged to the ESD voltage of interest, which is then discharged into the device through a  $1.5 \mathrm{k}\Omega$  resistor.

#### **Driver Output Protection**

Two mechanisms prevent excessive output current and power dissipation caused by faults or bus contention. The first, a foldback current limit on the driver output

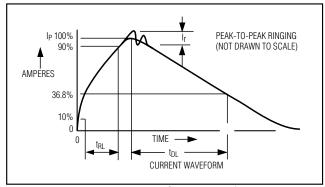


Figure 8b. Human Body Model Current Waveform

stage, provides immediate protection against short circuits over the whole common-mode voltage range. The second, a thermal shutdown circuit, forces the driver outputs into a high-impedance state if the die temperature exceeds +160°C. Normal operation resumes when the die temperature cools by +140°C, resulting in a pulsed output during continuous short-circuit conditions.

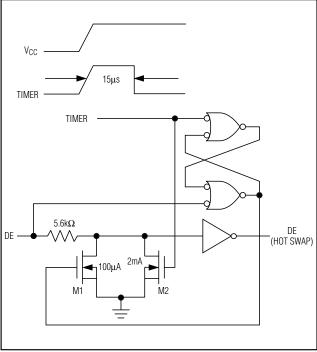


Figure 9. Simplified Structure of the Driver Enable Pin (DE)

### Hot-Swap Capability Hot-Swap Inputs

Inserting circuit boards into a hot, or powered backplane may cause voltage transients on DE, RE, and receiver inputs A and B that can lead to data errors. For example, upon initial circuit board insertion, the processor undergoes a power-up sequence. During this period, the highimpedance state of the output drivers makes them unable to drive the MAX3430 enable inputs to a defined logic level. Meanwhile, leakage currents of up to 10µA from the high-impedance output, or capacitively coupled noise from VCC or GND, could cause an input to drift to an incorrect logic state. To prevent such a condition from occurring, the MAX3430 features hot-swap input circuitry on DE to safeguard against unwanted driver activation during hot-swap situations. When VCC rises, an internal pulldown circuit holds DE low for at least 10µs, and until the current into DE exceeds 200µA. After the initial power-up sequence, the pulldown circuit becomes transparent, resetting the hot-swap tolerable input.

#### Hot-Swap Input Circuitry

At the driver enable input (DE), there are two NMOS devices, M1 and M2 (Figure 9). When VCC ramps from 0, an internal 15µs timer turns on M2 and sets the SR latch, which also turns on M1. Transistors M2, a 2mA current sink, and M1, a 100µA current sink, pull DE to GND through a  $5.6k\Omega$  resistor. M2 pulls DE to the disabled state against an external parasitic capacitance up to 100pF that may drive DE high. After 15µs, the timer deactivates M2 while M1 remains on, holding DE low against three-state leakage currents that may drive DE high. M1 remains on until an external current source overcomes the required input current. At this time, the SR latch resets M1 and turns off. When M1 turns off, DE reverts to a standard, high-impedance CMOS input. Whenever VCC drops below 1V, the input is reset.

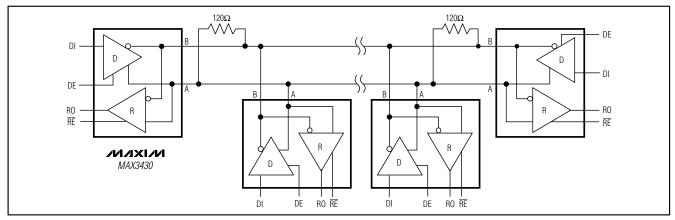


Figure 10. Typical RS-485 Network

#### **Applications Information**

#### 128 Transceivers on the Bus

The standard RS-485 receiver input impedance is  $12k\Omega$  (one-unit load), and a standard driver can drive up to 32-unit loads. The MAX3430 transceiver 1/4-unit-load receiver input impedance (48k $\Omega$ ) allows up to 128 transceivers connected in parallel on one communication line. Connect any combination of these devices, and/or other RS-485 devices, for a maximum of 32 unit loads to the line.

#### **RS-485 Applications**

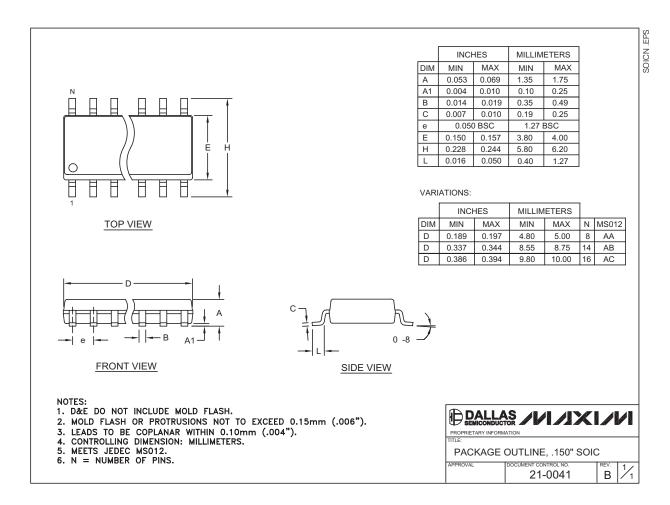
The MAX3430 transceiver provides bidirectional data communications on multipoint bus transmission lines. Figure 10 shows a typical network applications circuit. The RS-485 standard covers line lengths up to 4000ft. The signal line must be terminated at both ends in its characteristic impedance, and stub lengths off the main line kept as short as possible.

#### Chip Information

TRANSISTOR COUNT: 300 PROCESS: BICMOS

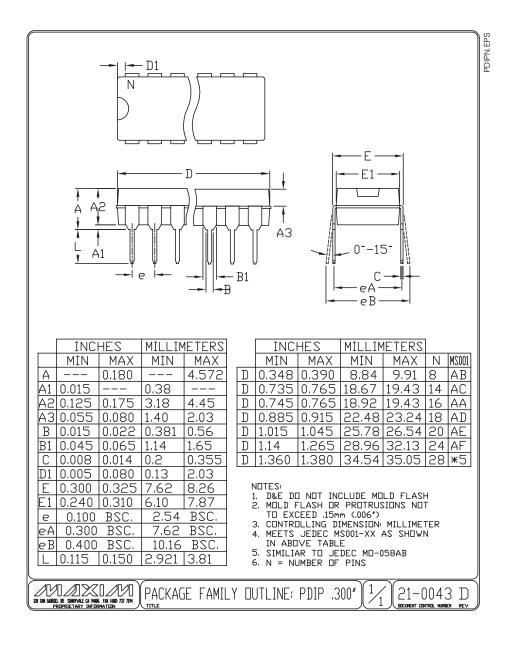
#### Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>.)



#### **Package Information (continued)**

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to <a href="https://www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>.)



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LTC1485CN8#PBF LTC1686IS8#PBF LTC488CN#PBF LTC1480IN8#PBF ADM3066EARMZ ADM3095EBRZ LTC487IN#PBF
LTC1482CMS8#PBF LTC488IN#PBF LTC486IN#PBF LTC1481IN8#PBF SN65HVD1470DR ADM3063EARZ ADM3068EARZ
ADM3064EARZ-R7 ADM3064EBRZ ADM3064EARZ ADM3065ETRMZ-EP ADM3066EBRMZ-R7 ADM3066ETRMZ-EP
ADM3095EARZ LTC1687IS#PBF LTC1686CS8#PBF LTC1481CS8#PBF LTC1485IS8#TRPBF LTC1482CS8#TRPBF LTC485CN8#PBF
SP488CS LTC1484CN8#PBF LTC1482CN8#PBF LTC1483IN8#PBF LTC1483CS8 LTC1483IS8 LTC1485IS8 LTC1518IS
LTC1689IS#PBF